

Light Avenue Premium Edition LED series is designed for high performance consumer applications. Remarkable light extraction is reached by a particular top emitting design with vertical chip structure. As this die can be driven at very high currents compared to the chip size, an outstanding cost vs. performance ratio can be obtained.



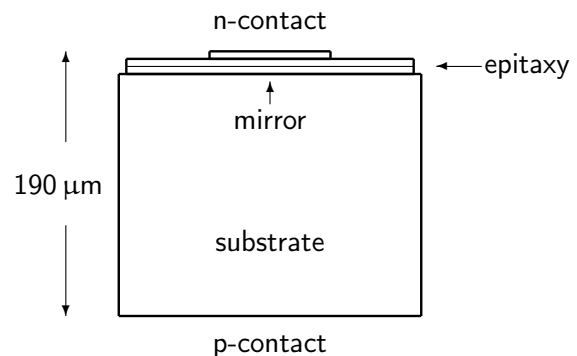
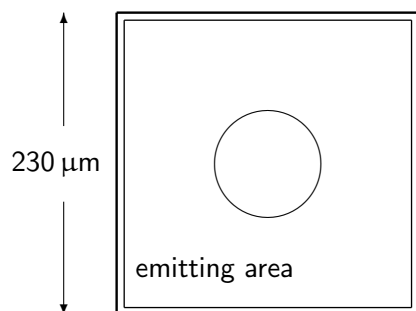
Features

- Lambertian radiation
- Optimized for SMT applications
- Grouping: radiant power, wavelength
- Highest brightness InGaN chip
- Top emitting device

Applications

- Solid state lighting
- LCD backlighting
- Lamps
- Displays
- Light indicators

Delineation



Mechanical characteristics

DESCRIPTION	MINIMUM	TYPICAL ¹	MAXIMUM
Chip size (μm)	205	230	255
Chip height (μm)	170	190	210
Bond pad diameter (μm)	80	90	100
Top contact	Cathode (n), gold		
Bottom contact	Anode (p), gold alloy		
Die attach	Epoxy bonding		

Electro-optical characteristics ($T_A = 25^\circ\text{C}$)²

PARAMETER	SYMBOL	CONDITION	MIN.	TYP. ¹	MAX.	UNIT
Forward voltage	V_F	$I_F = 10\text{ mA}$	2.70		3.50	V
Reverse voltage	V_R	$I_R = 10\ \mu\text{A}$	5.0			V
Dominant wavelength	λ_{dom}	$I_F = 10\text{ mA}$	455		465	nm
Radiant power	Φ_e	$I_F = 10\text{ mA}$	4.0	8.0		mW

Maximum ratings ($T_A = 25^\circ\text{C}$)³

PARAMETER	SYMBOL	VALUE	UNIT
Operating temperature range	T_{op}	-40...+85	°C
Forward current	I_F	30	mA
LED junction temperature	T_j	125	°C

Binning ($I_F = 10\text{ mA}$)⁴

	WAVELENGTH (NM)			
	455-460	457.5-462.5	460-465	
Radiant power (mW)	> 4.0	Y13	YM13	Z13
	> 5.0	Y14	YM14	Z14
	> 6.4	Y15	YM15	Z15
	> 8.0	Y16	YM16	Z16
	> 10.0	Y17	YM17	Z17
	> 12.5	Y18	YM18	Z18

Notes:

- The usage of LEDs in life-support devices or systems has to be expressly and written authorized by the supplier!
- Dice are sensitive to ESD.
- Dice are shipped on blue foil with or without frame and have therefore to be stored between 15 and 30°C and below 60% relative humidity.
- Lead free product - RoHS compliant.
- The information in this document is subject to change without notice and describes the die generally. It shall not be considered as assured characteristics or detailed specification.

- The quality level of the final visual inspection shall comply to an AQL of 1.0 (according to MIL-STD-105E, level II), if the customer performs an incoming visual inspection of a shipment.
- All chips are checked according to the "Failure Catalog of Light Avenue dice" dated 2009-11-14. If this document is not familiar to you, please request it at your next sales office.

¹Typical (Typ) data are defined as long-term production mean values. These values are not specified and only given for information.

²Measurements are done with an accuracy of $\pm 15\%$. Correlation to customer's equipment and products is required.

³Maximum ratings are package dependent and may differ between packages. The forward current is not limited by the die but by the effect of the LED junction temperature on the package. If you need more information on pulsed operation, please contact your next sales office about possible driving conditions. If not otherwise specified the maximum pulse current may not exceed the maximum current in continuous mode.

⁴There may be more than one bin on one single foil. Single bins cannot be ordered.